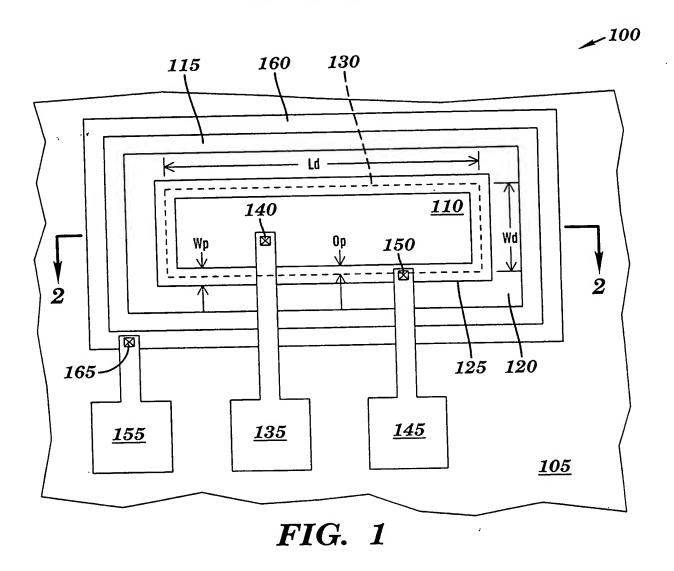
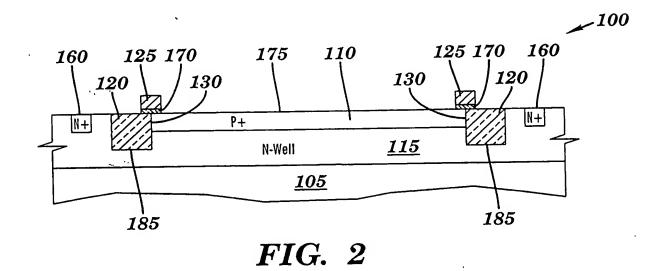
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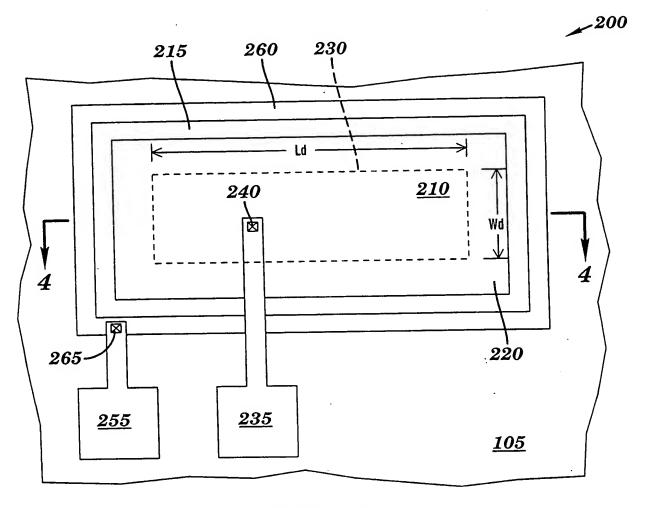
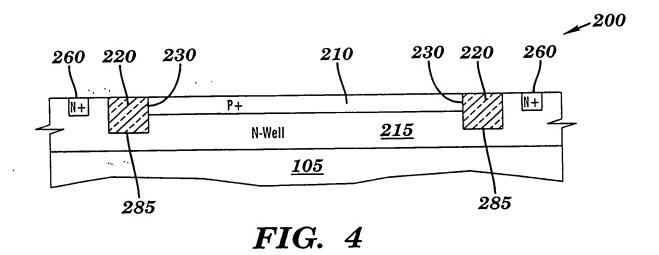


FIG. 3



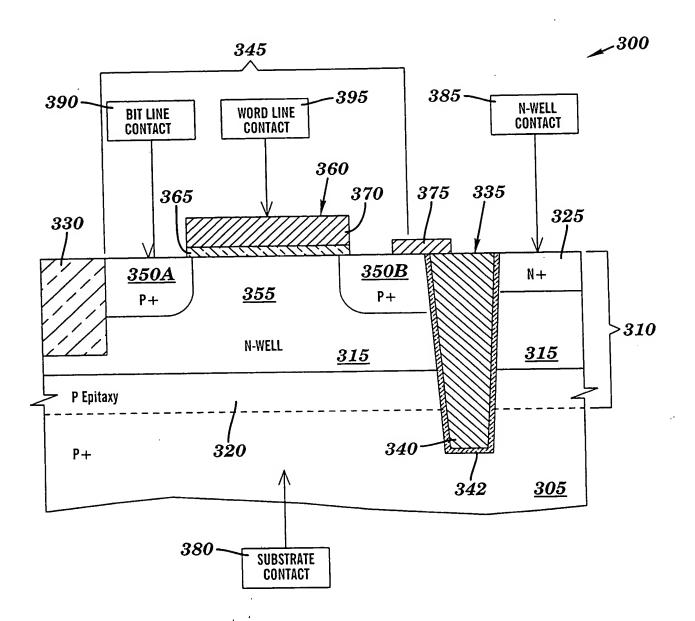


FIG. 5

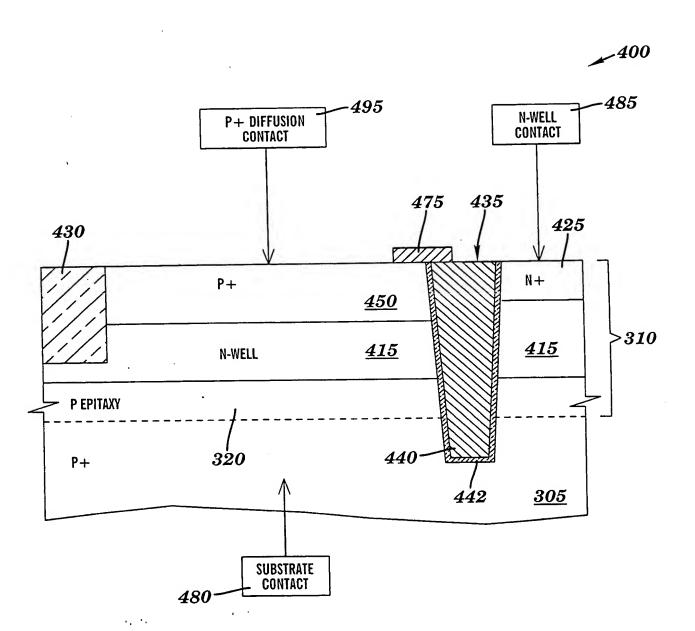
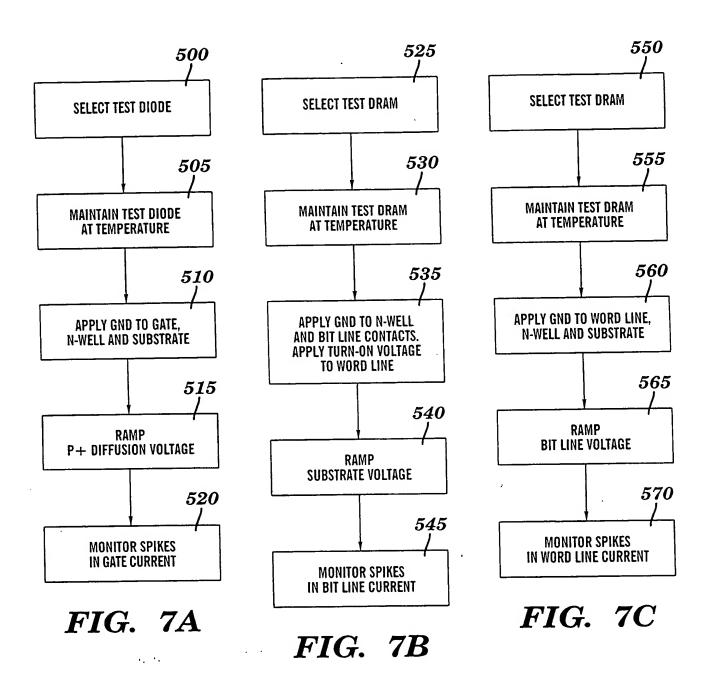


FIG. 6



## P+ POLYSILICON-BOUNDED DIODE WITHOUT STRESS-INDUCED DEFECTS

GATE AND DIFFUSION CURRENTS AT 180C AND 5nm THERMAL OXIDE

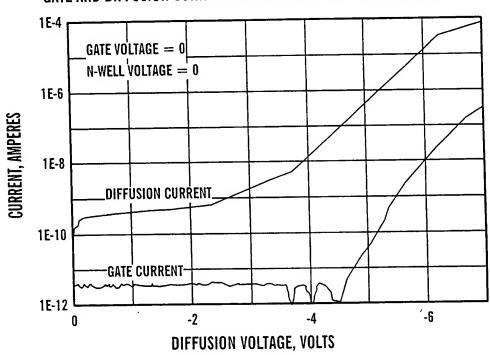


FIG. 8

## P+ POLYSILICON-BOUNDED DIODE WITH STRESS-INDUCED DEFECTS

GATE AND DIFFUSION CURRENTS AT 180C AND 5nm THERMAL OXIDE

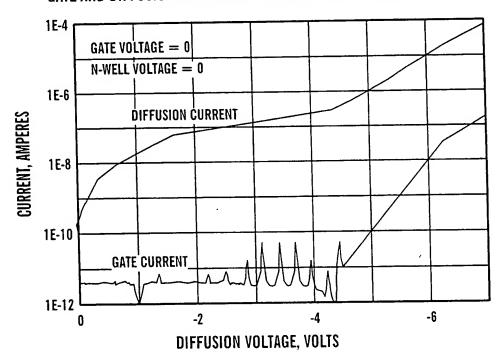
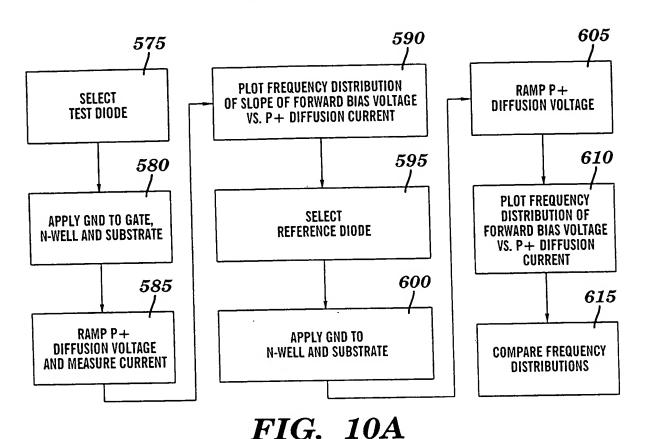


FIG. 9



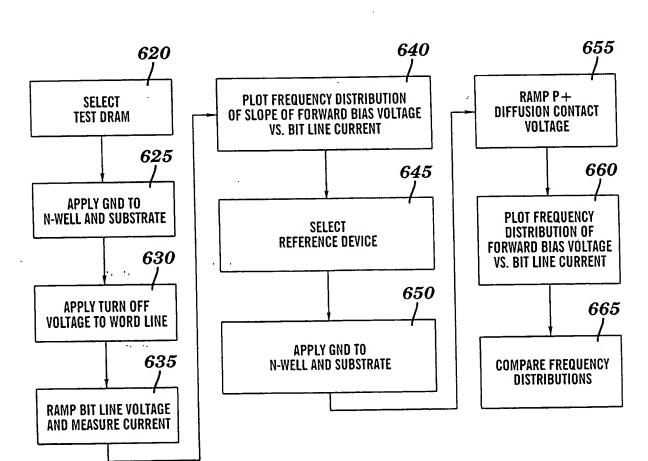


FIG. 10B

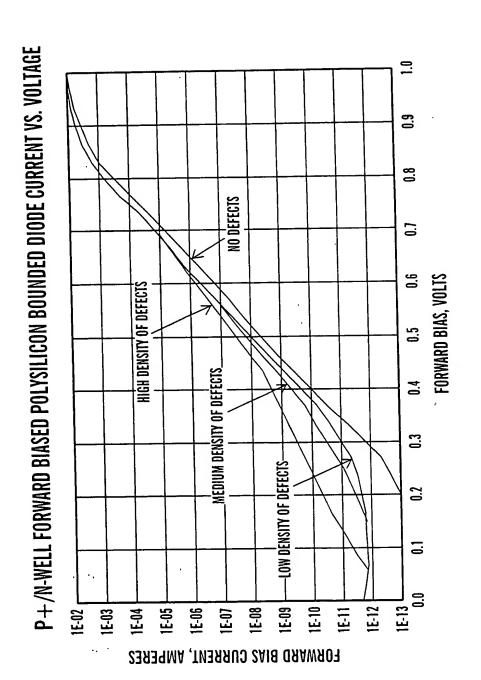
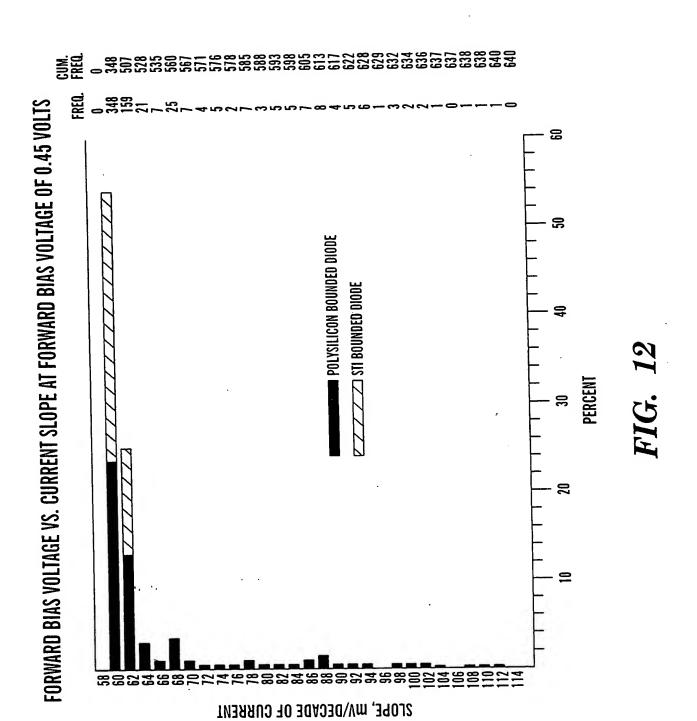


FIG. 11



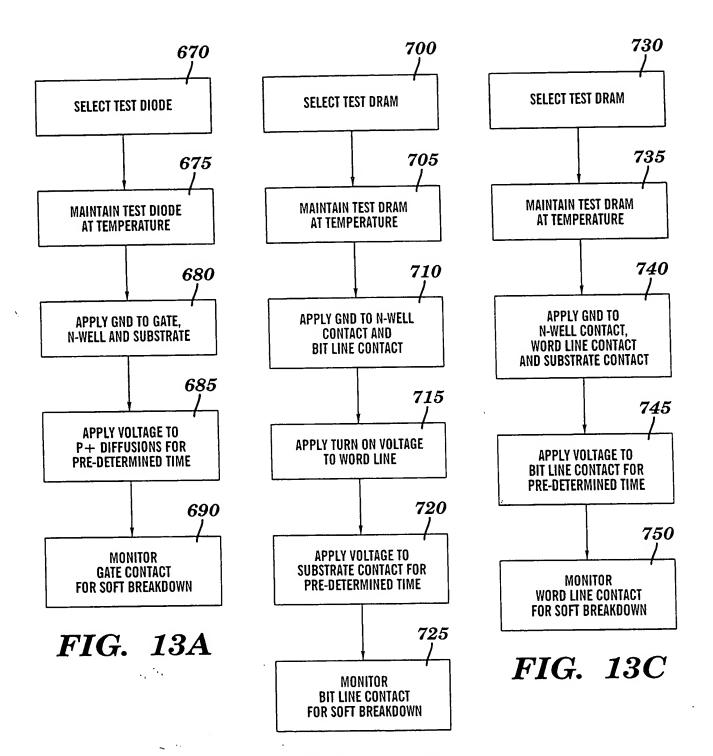


FIG. 13B

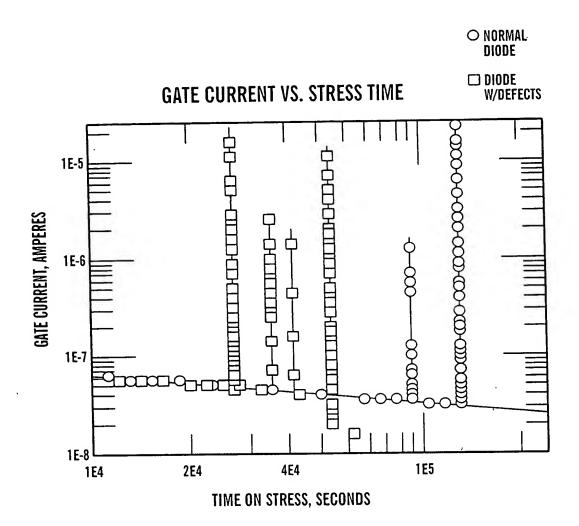
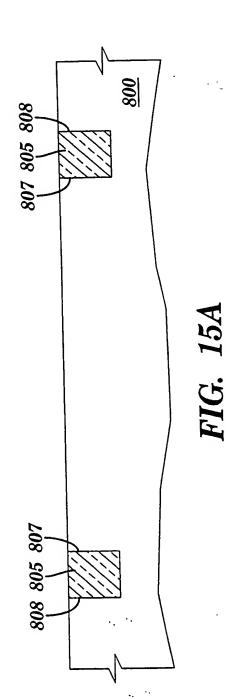
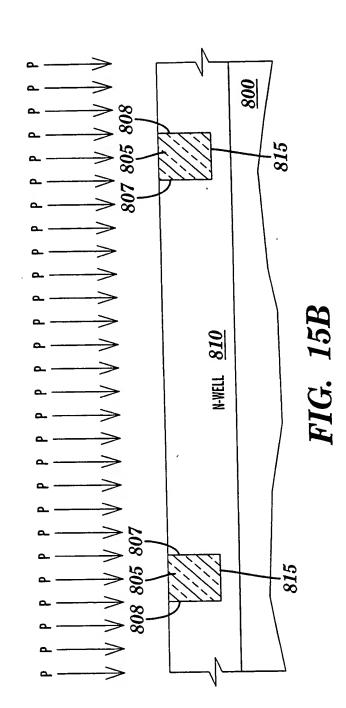


FIG. 14





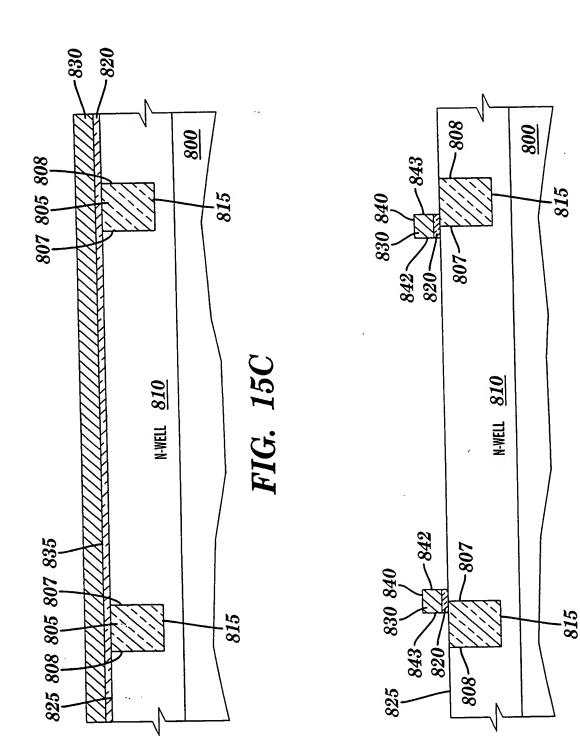
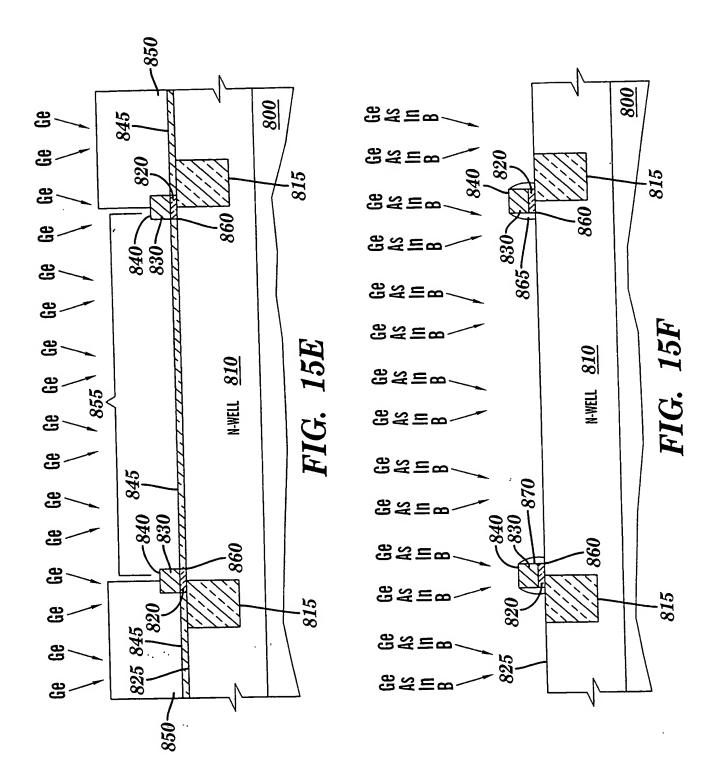
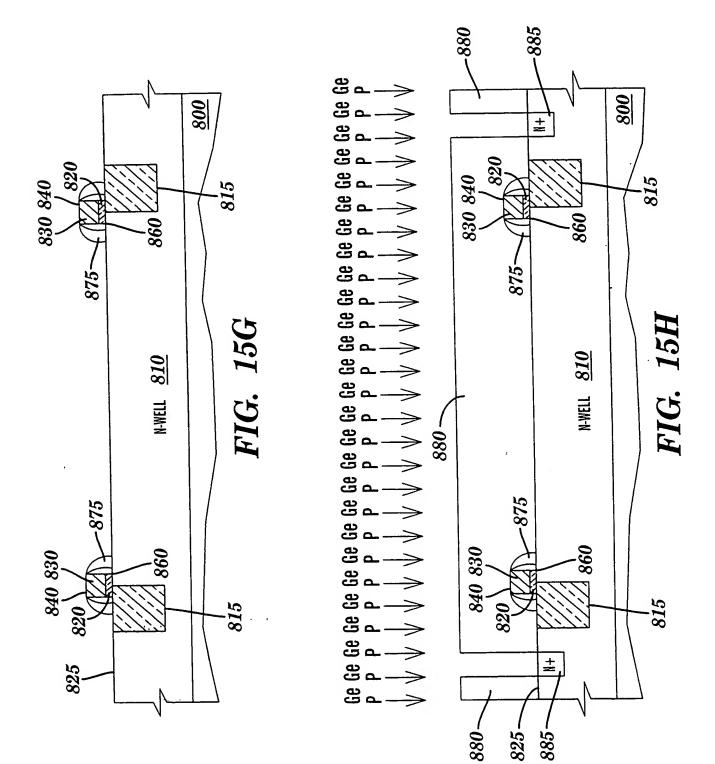


FIG. 15D





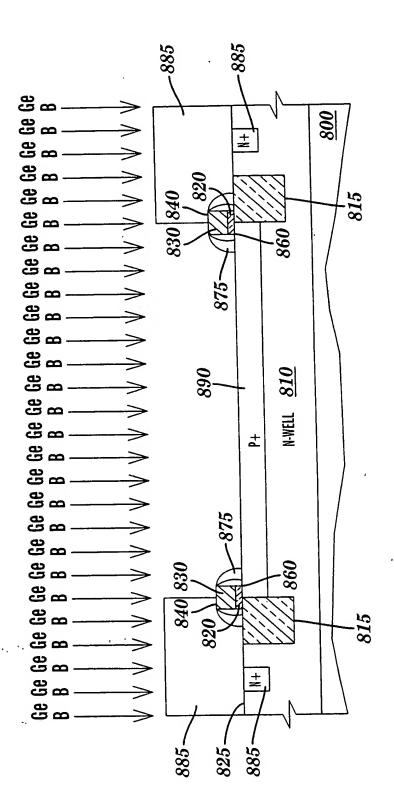
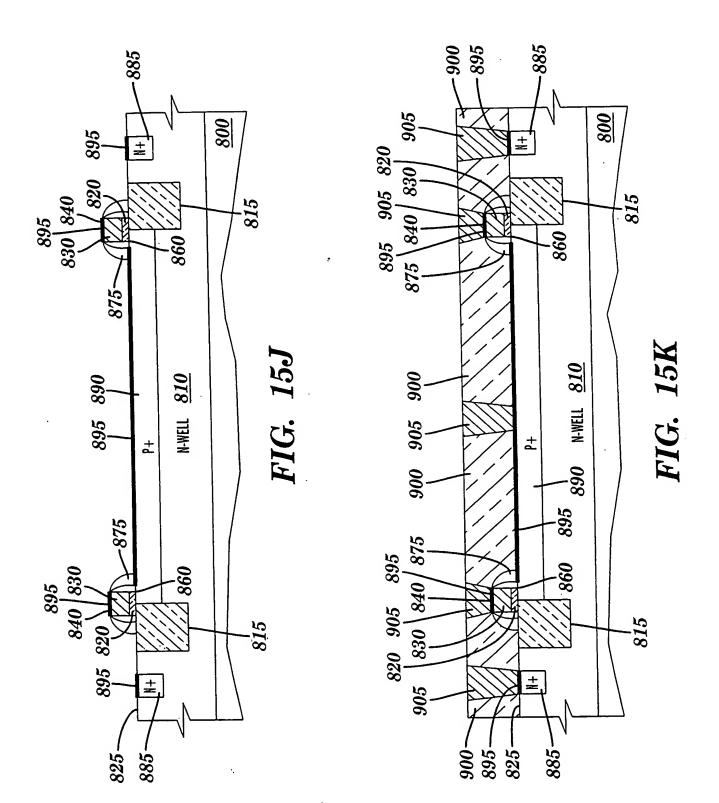
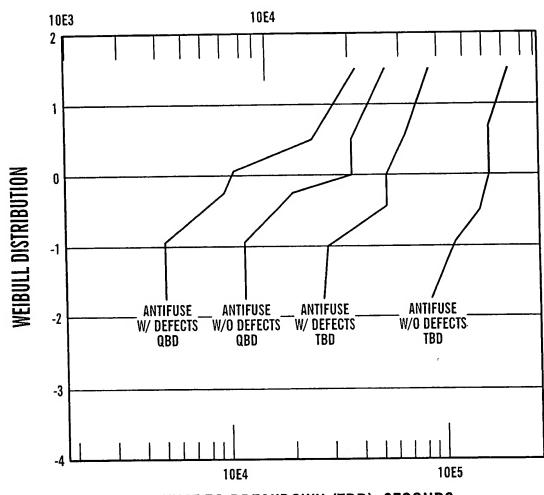


FIG. 15I

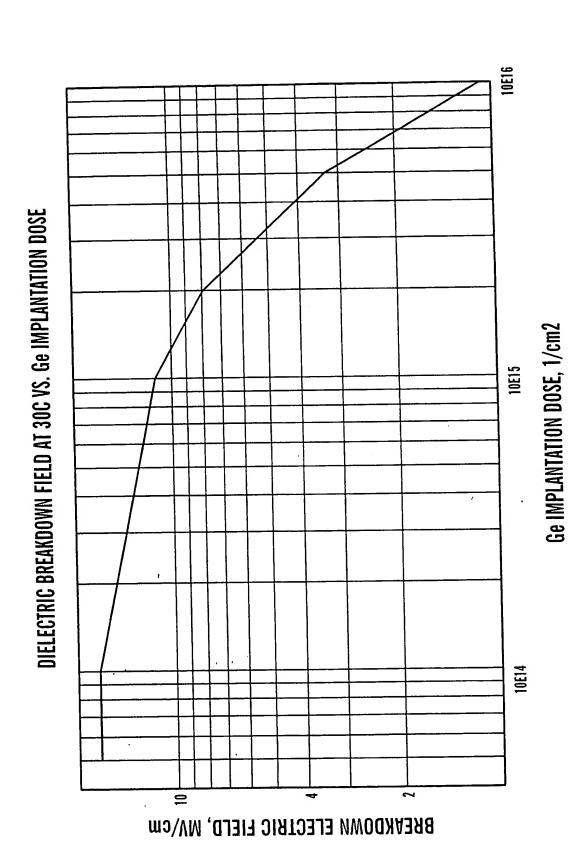


## CHARGE TO BREAKDOWN (QBD), C/cm2



TIME TO BREAKDOWN (TBD), SECONDS

FIG. 16



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FIG. 17

ВВЕРКООМИ ЛОГТАСЕ, У

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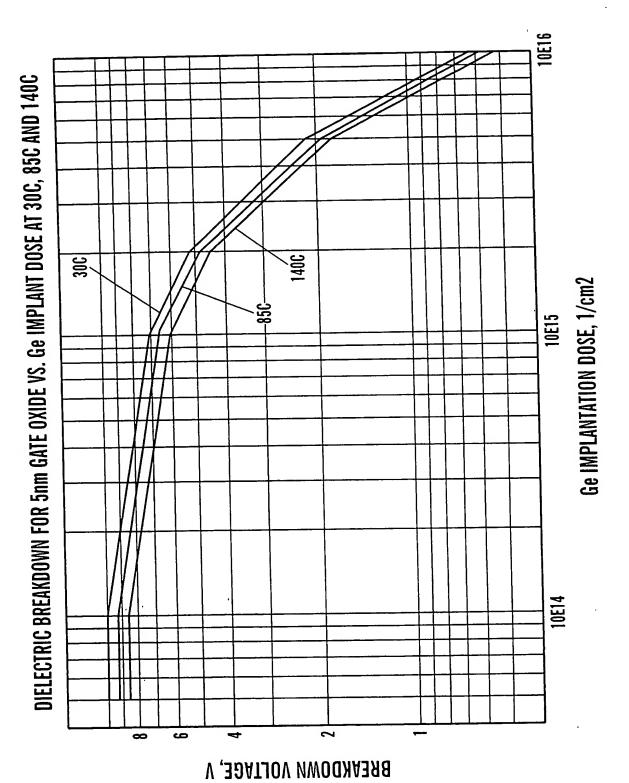


FIG. 19